

# MTP Presentation to HIPPI-6400

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# MTP History

- ◆ Developed for MT ferrule
- ◆ USConec introduced to North America in 1992
- ◆ Adopted by IBM for FTS in 1994
- ◆ IEC Standard 1754-7 in 1996
  - ⇒ Four Years in the making

# MTP Assemblies

- ◆ Multiple sources in North America, Europe, and Asia

AFL

Lucent

Sumitomo

AMP

Molex

W.L. Gore

CCI

Siecor

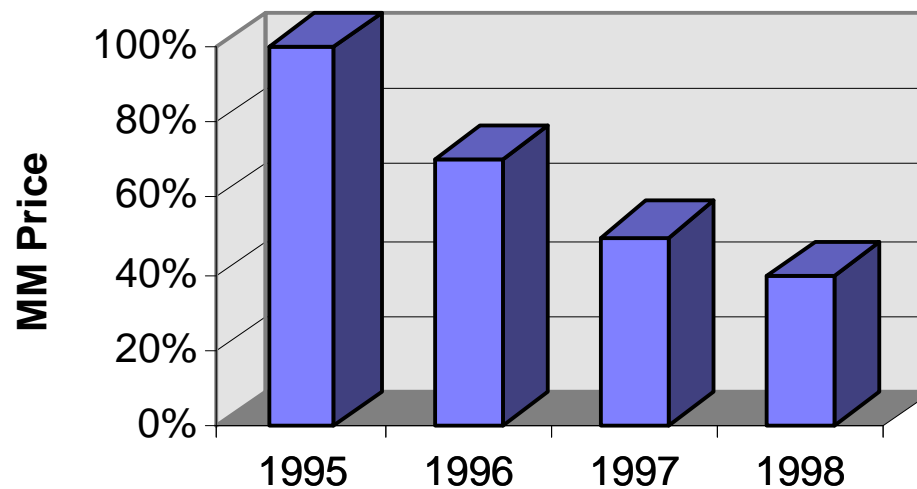
others...

# MTP Features

- ◆ Proven reliability in Data Centers
- ◆ Rugged design for patch panels and card edge applications
- ◆ Backplane version with zero-insertion force available
- ◆ Single-mode versions available today
- ◆ Duplex clip - later this year

# MTP Pricing History/ Future Forecast

**MTP Termination on 12 Fiber Ribbon**



# MTP vs. HIPPI Requirements

## 1. Existence

Engineering Samples 1990

Production Quantities 1992

## 2. Maturity

Only IEC Standard Multifiber Connector

## 3. Attenuation

MM

0.40 dB Average Non-Contacting

0.20 dB Average with “Direct Contact”

SM

0.30 dB Average with “Direct Contact”

# MTP vs. HIPPI Requirements

4. Durability ☒

1,000 cycles (No degradation)

5. Field Termination ☒

6. Environmental and Mechanical Performance ☒

See Conec MTP-012 Qualification Test  
Report

7. Height/Width ☒

8. Polarized ☒

9. Low Cost ☒